

MA2YD17

Silicon epitaxial planar type

For high frequency rectification

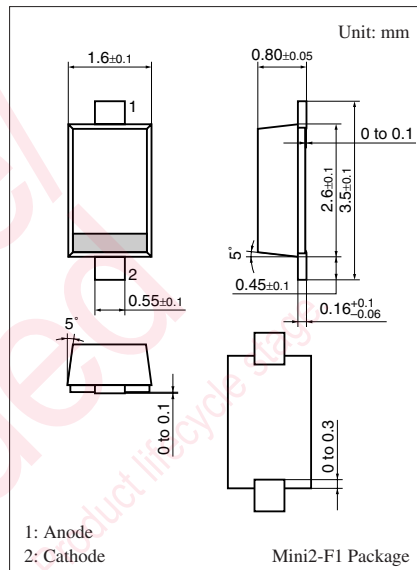
■ Features

- Reverse voltage $V_R = 100$ V is guaranteed

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	100	V
Maximum peak reverse voltage	V_{RM}	100	V
Forward current (Average)	$I_{F(AV)}$	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1.5	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: 2T

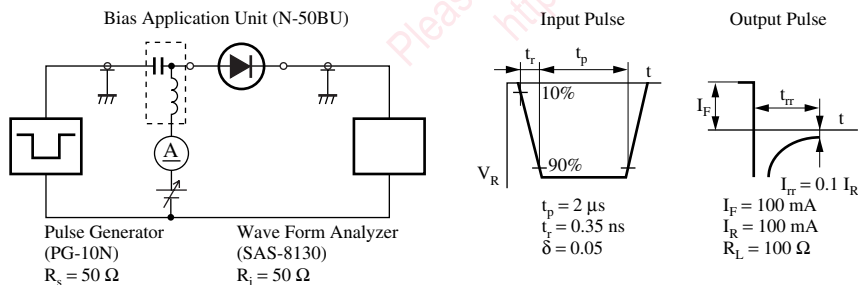
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

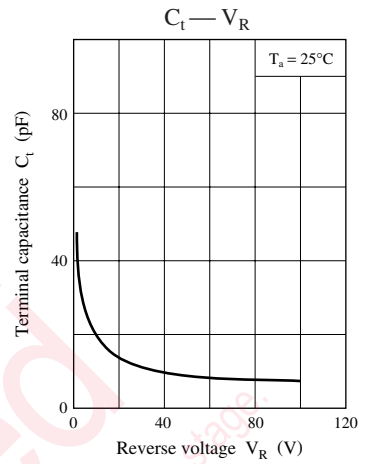
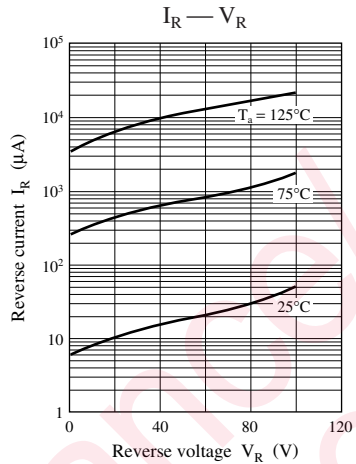
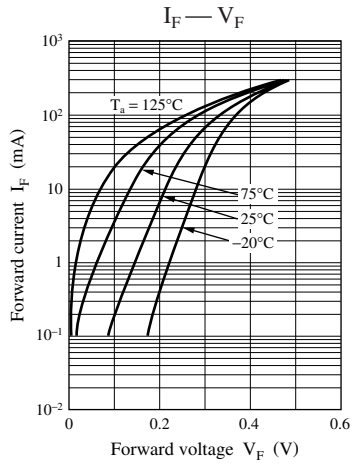
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 300$ mA		0.50	0.58	V
Reverse current	I_R	$V_R = 100$ V			200	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		100		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 0.1 I_R$, $R_L = 100$ Ω		7		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: t_{rr} measurement circuit





Maintenance/Discontinued includes following four Product lifecycle stages:
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
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